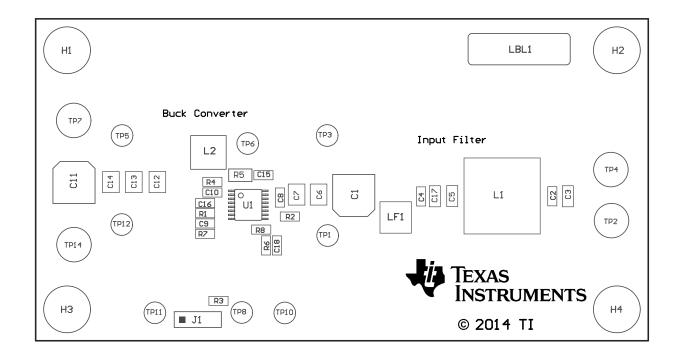
ZZ1 Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

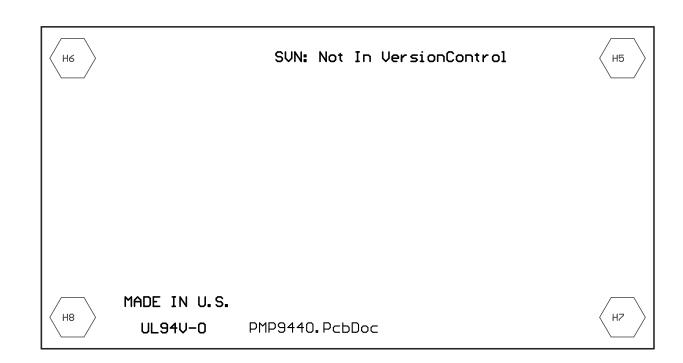
ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP9440	REV: E1	SVN REV:	Not In VersionControl
IGNORE -> Top Overlay				
PLOT NAME = Top Assembly Drawing	GENERATED : 10/13/	2015 3:17:31	PM	TEXAS INSTRUMENTS



ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP9440	REV: E1	SVN REV:	: Not In VersionControl
	Bottom Overlay <- 390001			
PLOT NAME = Bottom Assembly Drawing	GENERATED : 10/13/	2015 3:17:32	PM	TEXAS INSTRUMENTS

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